

Appl. No. : 10/031,622  
Filed : April 19, 2002

REMARKS

Claim 1 has been amended to clarify the invention. Support for the amendments to Claim 1 can be found at page 6, lines 19-23, and page 8, lines 1-11, for example. Claims 11 and 12 have been amended to rewrite in independent form including all of the limitations of the based claim. Claims 2, 3 and 7 have been canceled without prejudice. Claim 15 has been added. Support for Claim 15 can be found at page 8, lines 1-11, for example. Accordingly, Claims 1, 4-6 and 8-15 are pending in this application. The amendments do not constitute the addition of any new matter to the specification. Applicant respectfully requests entry of the amendments and reconsideration of the application in view of the amendments and the following remarks.

Rejection Under 35 U.S.C. § 102

Claims 1-9 and 14 have been rejected under 35 U.S.C. 102(b) as being anticipated by JP 8-217913 (please note that the Examiner mistakenly refers to this as Kawami et al.). The claims as amended herein could not be anticipated by the reference as explained below. Claim 1 is independent and the remaining claims are ultimately dependent on Claim 1.

Claim 1 as amended herein recites a moisture absorbing formed body comprising a hygroscopic agent and a resinous component, wherein the hygroscopic agent is at least one selected from the group consisting of CaO, BaO and SrO, and wherein the resinous component is at least one selected from the group consisting of fluorine-containing resin and polyolefin resin. According to the present invention, the moisture infiltrating into an electronic device or the like can be removed easily and certainly. Thus, a chance of moisture entering into the internal atmosphere is reduced, and an atmosphere having a high initial level of dryness can be established.

JP 8-217913 discloses a moisture regulating and gas absorbing molded body comprising a moisture regulating agent, a gas absorbing material, and a thermoplastic resin. However, JP 8-217913 does not disclose the use of CaO, BaO or SrO. JP 8-217913 merely discloses the mixture of MgO and Al<sub>2</sub>O<sub>3</sub> together with MgSO<sub>4</sub>·nH<sub>2</sub>O.

In addition, the molded body of JP 8-217913 regulates moisture and absorbs gas. Regulating moisture is different from removing moisture. In other words, the molded body of JP 8-217913 essentially requires the property of releasing or discharging moisture from the body in addition to absorbing moisture.

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In contrast, the present invention is directed to a moisture absorbing formed body. That is, the formed body of the present invention absorbs moisture but does not regulate moisture, i.e., keeping a specific level of moisture. Thus, the desirable property of the body of JP 8-217913 is totally different from that of the present invention.

In view of the foregoing, JP 8-217913 fails to disclose every element of the claimed invention, and withdrawal of the rejection under § 102 is respectfully requested.

Further, Claims 1-7, 10 and 14 have been rejected under 35 U.S.C. 102(e) as being anticipated by U.S. Patent 6,226,890B1 (Boroson).

Boroson discloses a method of desiccating an environment surrounding a moisture-sensitive electronic device sealed within an enclosure. However, Boroson fails to disclose the use of fluorine-containing resin or polyolefin resin. Boroson merely sets forth that "Currently preferred moisture-permeable binders are selected from the group consisting of cellulose acetates, epoxies, phenoxies, siloxanes, methacrylates, sulfones, phthalates, and amides" (see column 7, lines 8-11).

Boroson fails to teach fluorine-containing resin or polyolefin resin as recited in Claim 1. Accordingly, Boroson does not teach every element of the claimed invention, and withdrawal of the rejection under § 102 is respectfully requested.

Additionally, there is no motivation to conceive the formed body of the present invention by combining JP 8-217913 which aims to keep a specific level of moisture and Boroson disclosing a desiccation of moisture-sensitive electronic device which is used only for absorbing moisture.

#### Objection of Claims 11-13

Claims 11-13 have been objected to because they are dependent on the rejected claim. However, Claims 11 and 12 have been rewritten in independent form including all of the limitations of the based claim, thereby obviating the objection. Claim 13 is dependent on the amended Claim 12. Applicant respectfully requests that Claims 11-13 be allowable.

#### New Claim 15

Claim 15 has been added. Claim 15 is depend on Claim 1, and at least for this reason, this claims could not be anticipated by the references as with Claim 1. Further, Claim 15 recites specific fluorine-containing resins which are not taught by the references. It is respectfully submitted that Claim 15 is patentable.



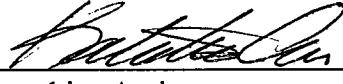
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**CONCLUSION**

In light of the Applicant's foregoing Remarks, it is respectfully submitted that the present application is in condition for allowance. Should the Examiner have any remaining concerns which might prevent the prompt allowance of the application, the Examiner is respectfully invited to contact the undersigned at the telephone number appearing below.

Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410. A duplicate copy of this sheet is enclosed.

Respectfully submitted,  
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